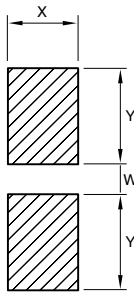


Recommended land pattern and size

(Vertical chip type)

- Standard type



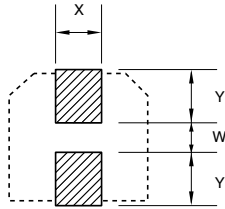
(Unit : mm)

Case Size $\phi D \times L$	Land Size			Thickness of Solder paste
	X	Y	W	
4×4.5, 5.3, 5.7, 5.8	1.6	2.6	1.0	0.15
5×4.5, 5.3, 5.7, 5.8	1.6	3.0	1.4	0.15
6.3×4.5, 5.3, 5.7, 5.8	1.6	3.6	1.9	0.15
6.3×7.7	1.6	3.6	1.9	0.15
8×6.5, 8.7	1.6	*4.0	*2.1	0.15
8×10, 10.5	2.5	*3.5	*3.0	0.15
10×8.7, 10, 10.5, 12.5	2.5	*4.0	*4.0	0.15
12.5×13.5	3.2	6.0	4.0	0.15

* For Vibration resistance use
 $\phi 8 \times 6.5$ Y=4.5 W=1.0
 $\phi 8 \times 10, \phi 8 \times 10.5$ Y=4.0 W=2.5
 $\phi 10 \times 10, \phi 10 \times 10.5$ Y=4.5 W=3.0
 $\phi 10 \times 12.5$ Y=4.5 W=3.0

- For vibration resistance type

VTZ, VTD, VTT, VTQ, VTV, VMH, VMD, VMJ, VMF, VME, HT1, HTK, HTX, HTQ series



(Unit : mm)

Case Size ϕD	Land Size			Thickness of Solder paste
	X	Y	W	
6.3	3.0	4.0	1.6	0.20
8	5.0	4.0	2.5	0.20
10	5.0	4.8	3.6	0.20
12.5	7.0	6.6	3.2	0.20
16	10.5	7.8	5.0	0.20
18	10.5	8.8	5.0	0.20

NOTE : Design, Specifications are subject to change without notice.
 It is recommended that you shall obtain technical specifications from ELNA to ensure that the component is suitable for your use.